



TMS Members Receive AAAS Fellow Distinction; Welcome New Members

Eight TMS Members Honored by AAAS

Congratulations to the following TMS members for being honored by the American Association for the Advancement of Science (AAAS) as 2020 Fellows. According to AAAS, “Fellows are a distinguished cadre of scientists, engineers, and innovators who have been recognized for their achievements across disciplines.” They were elected in October 2020 and chosen out of 489 individuals worldwide, in 24 different AAAS section affiliations.

Section on Chemistry

Paul V. Braun

University of Illinois at Urbana-Champaign
TMS member since 2013

Jiaxing Huang

Northwestern University
TMS member since 2012

Section on Engineering

L. Catherine Brinson

Duke University
TMS member since 2002

Kristen P. Constant

Iowa State University
TMS member since 2015

Ju Li

Massachusetts Institute of Technology
TMS member since 2003

Uday B. Pal

Boston University
TMS member since 1992, recipient of the 2015 Extraction & Processing Division Distinguished Lecture Award, and co-editor-in-chief of the Journal of Sustainable Metallurgy

Robert O. Ritchie

University of California, Berkeley
TMS member since 1976, recipient of the 2020 William D. Nix Award, 2017 Morris Cohen Award, 2010 Institute of Metals/Robert Franklin Mehl Award, and 2004 TMS Fellow

Section on Societal Impacts of Science and Engineering

Oladele (Dele) A. Ogunseitan

University of California, Irvine,
TMS member since 2005

member news

Share the good news about your professional accomplishments! Contact Kaitlin Calva, JOM Magazine Managing Editor, at kcalva@tms.org. Please note that only news submitted by current TMS members will be considered.



Paul V. Braun



Jiaxing Huang



L. Catherine Brinson



Kristen P. Constant



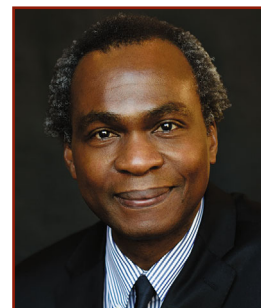
Ju Li



Uday B. Pal



Robert O. Ritchie



Oladele (Dele) A. Ogunseitan

TMS Welcomes New Members

The TMS Board of Directors approved professional membership for the following individuals at its December 2020 meeting. Please join us in congratulating and welcoming them to all the privileges and benefits of TMS membership.

Aceves, Maureen; Oxford University, United Kingdom	Fu, Wentao; United States	Meng, Fan; QuesTek Innovations LLC, United States
Al-Lehyani, Ibrahim; King Abdulaziz University, Saudi Arabia	Fuerst, Jacob D.; United States	Porter, Eric I.; University of Alberta, Canada
Amini, Shahram; Pulse Technologies Inc., United States	Gagnon, Jessie; Laval University, Canada	Romani, Nadia; Rio Tinto, Canada
Andermann, Lawrence J.; Suez, United States	Gupta, Ankur; Indian Institute of Technology Jodhpur, India	Santala, Melissa K.; Oregon State University, United States
Apena, Azeez; United States	Holota, Radek; University of West Bohemia, Czech Republic	Schaadt, Steven T.; Howmet Aerospace, United States
Arai, Noriaki; QuesTek Innovations LLC, United States	House, Stephen D.; University of Pittsburgh, United States	Sharma, Prince; India
Beach, Elvin; The Ohio State University, United States	Hunert, Daniela; Germany	Shu, Wenya; Virginia Polytechnic Institute and State University, United States
Birnbaum, Peter; Chemnitz University of Technology, Germany	Jacobsohn, Luiz G.; Clemson University, United States	Skala, Jiri; University of West Bohemia, Czech Republic
Brueck, Ekkes; Delft University of Technology, Netherlands	Jain, Vipin; National Physical Laboratory, India	Sobotova, Lenka; University of West Bohemia, Czech Republic
Chan, Andrew; ALD Vacuum Technologies North America Inc., United States	Kapoor, Monica; Novelis, United States	Sohrabi, Sajad; Islamic Republic of Iran
Chen, Yi-Sheng; The University of Sydney, Australia	Khalaj, Omid; University of West Bohemia, Czech Republic	Sorkin Samuel; QuesTek Innovations LLC, United States
Choi, Hongseok; Clemson University, United States	Klenam, Desmond E.P.; South Africa	Souza, Flavio; United States
Colpitts, Tanner D.; United States	Kolel-Veetil, Manoj; Naval Research Laboratory, United States	Stadler, Ctibor; University of West Bohemia, Czech Republic
Cristante, Angelo; United States	Korotov, Anne-Sophie; United Kingdom	Thamizhirai, Selvan; United Kingdom
D'Abreu, Jose Carlos; Catholic University, Brazil	Koucky, Vaclav; University of West Bohemia, Czech Republic	Unruh, Bryan L.; NuWay Solutions LLC, United States
Dos Santos, Igor Cuzzuol; AMG Brasil, Brazil	Kua, Harn-wei; National University of Singapore, Singapore	Wilkinson, Mark; United Kingdom
Dowdle, John; Old Hickory Clay Company, United States	Lin, Jeffrey D.; QuesTek Innovations LLC, United States	Yu, XiaoXiang; Novelis Inc., United States
	Macha, John; United States	
	Massie, Grant Nicol; Gates Power Transmission Ltd., United Kingdom	

**Membership grade recommendations are based on a review of credentials provided by the individuals. These credentials are taken on the honor system and not independently verified, except by exception.*